

Title (en)

Method of plating a bonded magnet and a bonded magnet carrying a metal coating.

Title (de)

Verfahren zur Plattierung eines Verbundmagneten sowie Verbundmagnet mit einem Metallüberzug.

Title (fr)

Procédé de revêtement d'un aimant composite et aimant composite ainsi revêtu.

Publication

**EP 0502475 A2 19920909 (EN)**

Application

**EP 92103609 A 19920303**

Priority

- JP 6397691 A 19910304
- JP 6397791 A 19910304
- JP 6397891 A 19910304
- JP 6397991 A 19910304

Abstract (en)

A closely adherent metal coating having a uniform thickness and substantially free from pinholes is formed on the porous surface of a bonded magnet to improve its oxidation and corrosion resistance without lowering its magnetic properties. The coating is formed by electroplating from an aqueous solution not containing chlorine, and having a pH of 5 or above. More particularly, the solution contains mainly nickel sulfate, an electrolyte in the form of an organic acid salt not containing chlorine, and a basic electrolyte not containing chlorine, and forms a nickel coating on the magnet surface. <IMAGE>

IPC 1-7

**C25D 3/12**; **C25D 5/00**; **H01F 1/053**; **H01F 41/02**

IPC 8 full level

**C25D 3/12** (2006.01); **H01F 1/057** (2006.01); **H01F 41/02** (2006.01)

CPC (source: EP US)

**C25D 3/12** (2013.01 - EP US); **H01F 1/0578** (2013.01 - EP US); **H01F 41/026** (2013.01 - EP US); **Y10T 428/12049** (2015.01 - EP US); **Y10T 428/12083** (2015.01 - EP US); **Y10T 428/12146** (2015.01 - EP US)

Cited by

KR100607297B1; EP0984464A3; EP1441047A4; EP1455368A4; EP0712198A4; KR20190093280A; GB2321647A; US5985124A; GB2321647B; EP1493847A3; EP1024506A1; EP1028437A4; CN110506315A; EP3611740A4; US6251196B1; US11462959B2; US7156928B2; WO02063070A1; US7449100B2; US6406611B1; US6399150B1; US7053745B2; KR100374398B1

Designated contracting state (EPC)

DE FR GB

DOCDB simple family (publication)

**EP 0502475 A2 19920909**; **EP 0502475 A3 19930922**; **EP 0502475 B1 19970625**; DE 69220519 D1 19970731; DE 69220519 T2 19980219; US 5302464 A 19940412

DOCDB simple family (application)

**EP 92103609 A 19920303**; DE 69220519 T 19920303; US 84564592 A 19920304